

Single P-channel MOSFET

ELM17411GA-S

■ General description

ELM17411GA-S uses advanced trench technology to provide excellent $R_{ds(on)}$, low gate charge and operation with gate voltages as low as 1.8V.

■ Features

- $V_{ds} = -20V$
- $I_d = -1.8A$ ($V_{gs} = -4.5V$)
- $R_{ds(on)} < 120m\Omega$ ($V_{gs} = -4.5V$)
- $R_{ds(on)} < 150m\Omega$ ($V_{gs} = -2.5V$)
- $R_{ds(on)} < 200m\Omega$ ($V_{gs} = -1.8V$)

■ Maximum absolute ratings

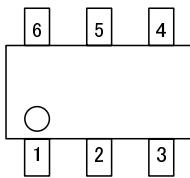
Parameter	Symbol	Limit	Unit	Note
Drain-source voltage	V_{ds}	-20	V	
Gate-source voltage	V_{gs}	± 8	V	
Continuous drain current Ta=25°C	I_d	-1.8	A	1
Ta=70°C		-1.5		
Pulsed drain current	I_{dm}	-10	A	2
Power dissipation Ta=25°C	P_d	0.625	W	1
Ta=70°C		0.400		
Junction and storage temperature range	T_j, T_{stg}	-55 to 150	°C	

■ Thermal characteristics

Parameter		Symbol	Typ.	Max.	Unit	Note
Maximum junction-to-ambient	t≤10s	$R_{\theta ja}$	160	200	°C/W	1
Maximum junction-to-ambient	Steady-state		180	220	°C/W	
Maximum junction-to-lead	Steady-state	$R_{\theta jl}$	130	160	°C/W	3

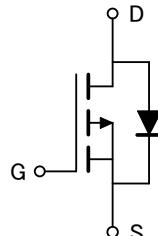
■ Pin configuration

SC-70-6 (TOP VIEW)



Pin No.	Pin name
1	DRAIN
2	DRAIN
3	GATE
4	SOURCE
5	DRAIN
6	DRAIN

■ Circuit



Single P-channel MOSFET

ELM17411GA-S

■ Electrical characteristics

$T_a=25^\circ C$

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
STATIC PARAMETERS						
Drain-source breakdown voltage	BVdss	$Id=-250\ \mu A, Vgs=0V$	-20			V
Zero gate voltage drain current	Idss	Vds=-16V			-1	μA
		Vgs=0V	Tj=55°C		-5	
Gate-body leakage current	Igss	Vds=0V, Vgs=±8V			±100	nA
Gate threshold voltage	Vgs(th)	Vds=Vgs, Id=-250 μA	-0.40	-0.55	-0.80	V
On state drain current	Id(on)	Vgs=-4.5V, Vds=-5V	-10			A
Static drain-source on-resistance	Rds(on)	Vgs=-4.5V		95	120	$m\Omega$
		Id=-1.8A	Tj=125°C	129	160	
		Vgs=-2.5V, Id=-1.6A		121	150	$m\Omega$
		Vgs=-1.8V, Id=-1A		155	200	$m\Omega$
Forward transconductance	Gfs	Vds=-5V, Id=-1.8A	4	7		S
Diode forward voltage	Vsd	Is=-1A, Vgs=0V		-0.83	-1.00	V
Max. body-diode continuous current	Is				-0.6	A
DYNAMIC PARAMETERS						
Input capacitance	Ciss	Vgs=0V, Vds=-10V, f=1MHz		524		pF
Output capacitance	Coss			93		pF
Reverse transfer capacitance	Crss			73		pF
Gate resistance	Rg	Vgs=0V, Vds=0V, f=1MHz		12		Ω
SWITCHING PARAMETERS						
Total gate charge	Qg	Vgs=-4.5V, Vds=-10V Id=-1.8A		6.24		nC
Gate-source charge	Qgs			0.52		nC
Gate-drain charge	Qgd			1.84		nC
Turn-on delay time	td(on)	Vgs=-4.5V, Vds=-10V Rl=5.6 Ω , Rgen=3 Ω		10.5		ns
Turn-on rise time	tr			11.8		ns
Turn-off delay time	td(off)			54.5		ns
Turn-off fall time	tf			24.7		ns
Body diode reverse recovery time	trr	If=-1.8A, dl/dt=100A/ μs		24.7		ns
Body diode reverse recovery charge	Qrr	If=-1.8A, dl/dt=100A/ μs		8.2		nC

NOTE :

1. The value of $R_{\theta ja}$ is measured with the device mounted on 1in² FR-4 board of 2oz. Copper, in still air environment with $T_a=25^\circ C$. The value in any given applications depends on the user's specific board design, The current rating is based on the $t \leq 10s$ thermal resistance rating.
2. Repetitive rating, pulse width limited by junction temperature.
3. The $R_{\theta ja}$ is the sum of the thermal impedance from junction to lead $R_{\theta jl}$ and lead to ambient.
4. The static characteristics in Figures 1 to 6 are obtained using 80 μs pulses, duty cycle 0.5%max.
5. These tests are performed with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with $T_a=25^\circ C$. The SOA curve provides a single pulse rating.



Single P-channel MOSFET

ELM17411GA-S

■ Typical electrical and thermal characteristics

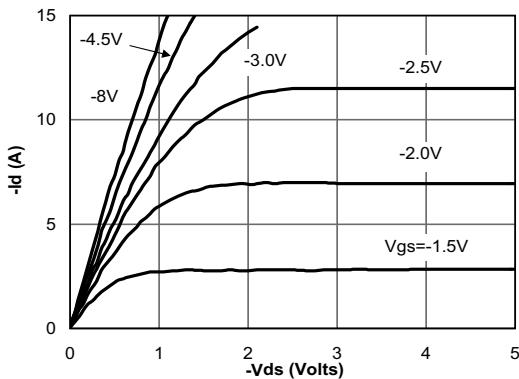


Fig 1: On-Region Characteristics

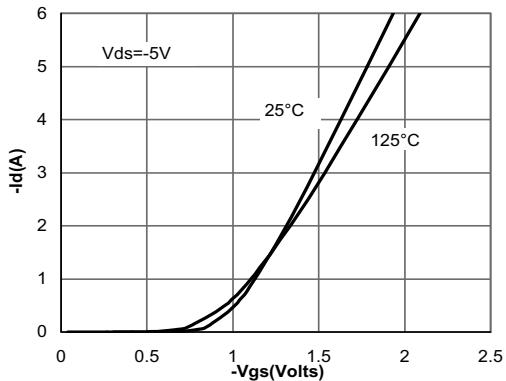


Figure 2: Transfer Characteristics

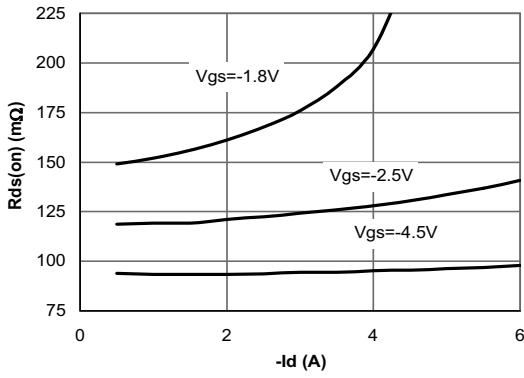


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

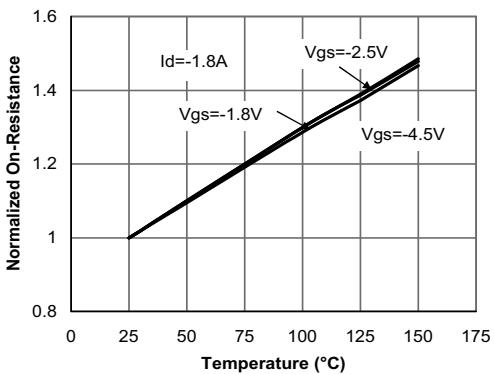


Figure 4: On-Resistance vs. Junction Temperature

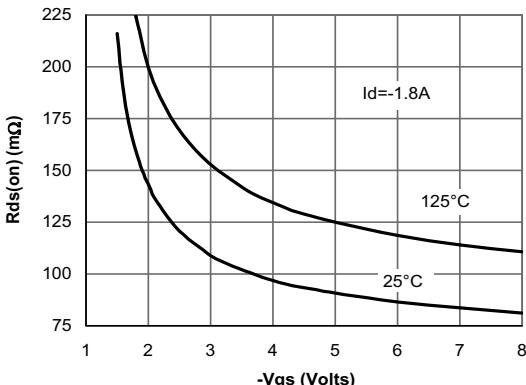


Figure 5: On-Resistance vs. Gate-Source Voltage

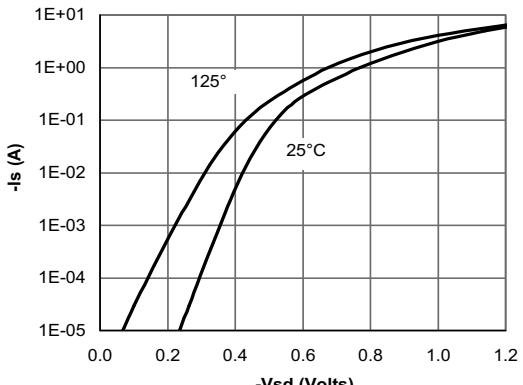


Figure 6: Body-Diode Characteristics

Single P-channel MOSFET

ELM17411GA-S

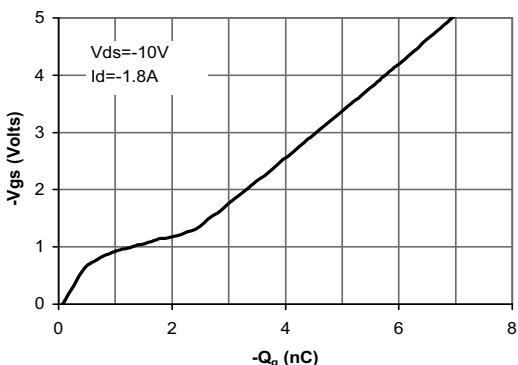


Figure 7: Gate-Charge Characteristics

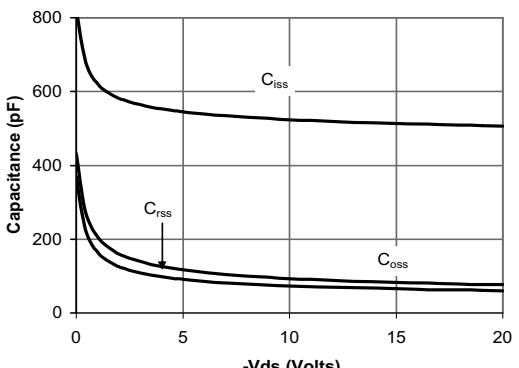


Figure 8: Capacitance Characteristics

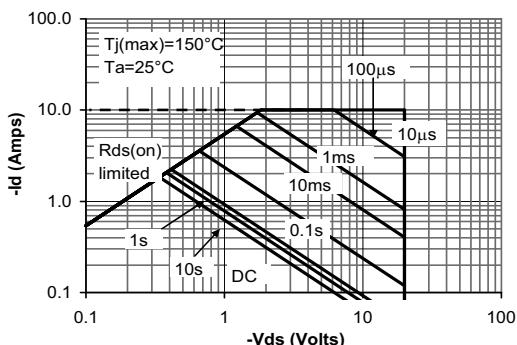


Figure 9: Maximum Forward Biased Safe Operating Area (Note E)

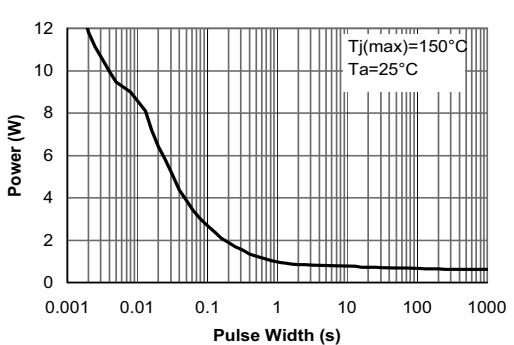


Figure 10: Single Pulse Power Rating Junction-to-Ambient (Note E)

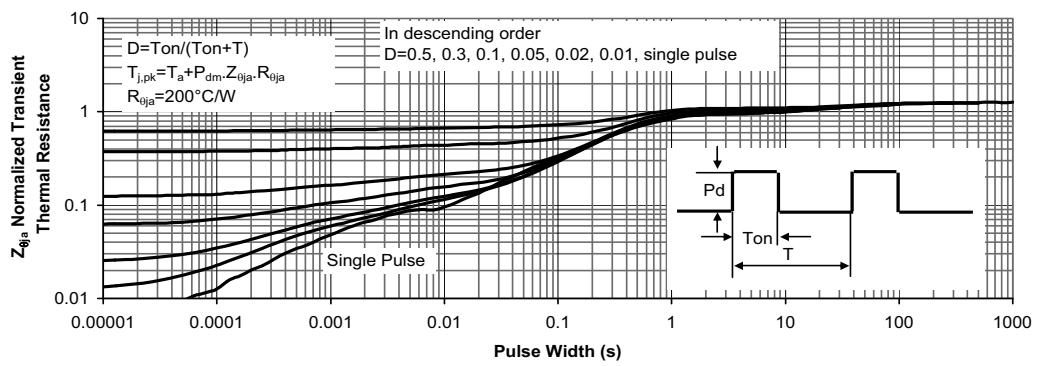


Figure 11: Normalized Maximum Transient Thermal Impedance